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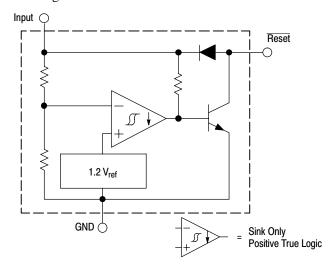
Undervoltage Sensing Circuit

The MC34064 is an undervoltage sensing circuit specifically designed for use as a reset controller in microprocessor-based systems. It offers the designer an economical solution for low voltage detection with a single external resistor. The MC34064 features a trimmed-in-package bandgap reference, and a comparator with precise thresholds and built-in hysteresis to prevent erratic reset operation. The open collector reset output is capable of sinking in excess of 10 mA, and operation is guaranteed down to 1.0 V input with low standby current. The MC devices are packaged in 3-pin TO-92, micro size TSOP-5, 8-pin SOIC-8 and Micro8™ surface mount packages. The NCV device is packaged in SOIC-8 and TO-92.

Applications include direct monitoring of the 5.0 V MPU/logic power supply used in appliance, automotive, consumer and industrial equipment.

Features

- Trimmed-In-Package Temperature Compensated Reference
- Comparator Threshold of 4.6 V at 25°C
- Precise Comparator Thresholds Guaranteed Over Temperature
- Comparator Hysteresis Prevents Erratic Reset
- Reset Output Capable of Sinking in Excess of 10 mA
- Internal Clamp Diode for Discharging Delay Capacitor
- Guaranteed Reset Operation with 1.0 V Input
- Low Standby Current
- Economical TO-92, TSOP-5, SOIC-8 and Micro8 Surface Mount Packages
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes
- Pb-Free Packages are Available



This device contains 21 active transistors.

Figure 1. Representative Block Diagram



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SOIC-8 D SUFFIX CASE 751

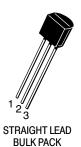


Micro8 DM SUFFIX CASE 846A



TSOP-5 SN SUFFIX CASE 483

- Pin 1. Ground
 - 2. Input
 - Reset
 NC
 - T. NO
 - 5. NC



1 2 3
BENT LEAD
TAPE & REEL

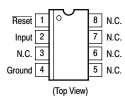
TO-92 P SUFFIX CASE 29

Pin 1. Reset 2. Input

Input
 Ground

PIN CONNECTIONS

AMMO PACK



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 7 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Input Supply Voltage	V _{in}	-1.0 to 10	V
Reset Output Voltage	V _O	10	V
Reset Output Sink Current (Note 2)	I _{Sink}	Internally Limited	mA
Clamp Diode Forward Current, Reset to Input Pin (Note 2)	lF	100	mA
Power Dissipation and Thermal Characteristics PSufix, Plastic Package Maximum Power Dissipation @ T _A = 25°C Thermal Resistance, Junction-to-Air DSufix, Plastic Package Maximum Power Dissipation @ T _A = 25°C Thermal Resistance, Junction-to-Air DM Suffix, Plastic Package Maximum Power Dissipation @ T _A = 25°C Thermal Resistance, Junction-to-Air		625 200 625 200 520 240	mW °C/W mW °C/W mW °C/W
Operating Junction Temperature	TJ	+150	°C
Operating Ambient Temperature MC34064 MC33064 NCV33064	T _A	0 to +70 -40 to +85 -40 to +125	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS (For typical values $T_A = 25^{\circ}C$, for min/max values T_A is the operating ambient temperature range that applies [Notes 3 and 4] unless otherwise noted.)

Characteristics	Symbol	Min	Тур	Max	Unit
COMPARATOR	•	•			
Threshold Voltage High State Output (V _{in} Increasing) Low State Output (V _{in} Decreasing) Hysteresis	V _{IH} V _{IL} V _H	4.5 4.5 0.01	4.61 4.59 0.02	4.7 4.7 0.05	V
RESET OUTPUT					
Output Sink Saturation	V _{OL}	- - -	0.46 0.15 -	1.0 0.4 0.1	V
Output Sink Current (V _{in} , Reset = 4.0 V)	I _{Sink}	10	27	60	mA
Output Off-State Leakage (V _{in} , Reset = 5.0 V)	I _{OH}	-	0.02	0.5	μΑ
Clamp Diode Forward Voltage, Reset to Input Pin (I _F = 10 mA)	V _F	0.6	0.9	1.2	V
TOTAL DEVICE					
Operating Input Voltage Range	V _{in}	1.0 to 6.5	-	-	V
Quiescent Input Current (V _{in} = 5.0 V)	I _{in}	-	390	500	μΑ

- 2. Maximum package power dissipation limits must be observed.
- 3. Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.
- 5. NCV prefix is for automotive and other applications requiring site and change control.

^{1.} ESD data available upon request.

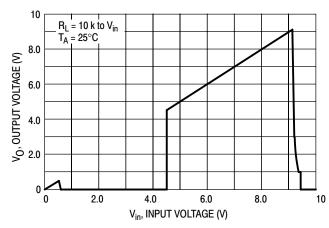


Figure 2. Reset Output Voltage versus Input Voltage

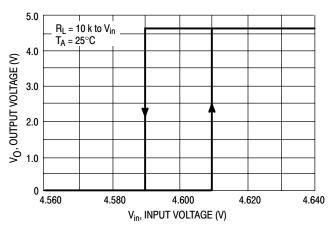


Figure 3. Reset Output Voltage versus Input Voltage

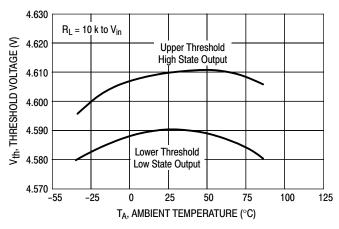


Figure 4. Comparator Threshold Voltage versus Temperature

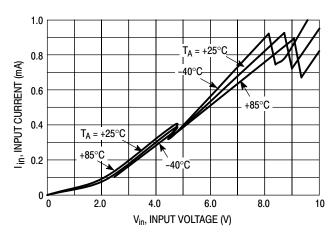


Figure 5. Input Current versus Input Voltage

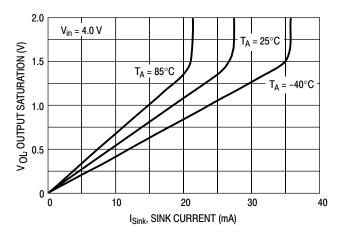


Figure 6. Reset Output Saturation versus Sink Current

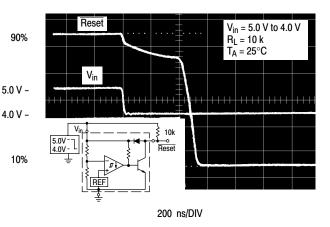


Figure 7. Reset Delay Time

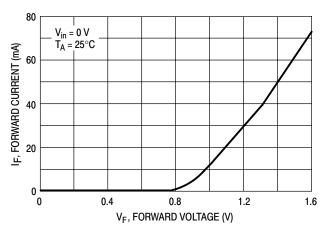


Figure 8. Clamp Diode Forward Current versus Voltage

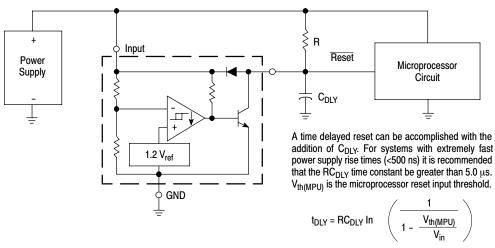
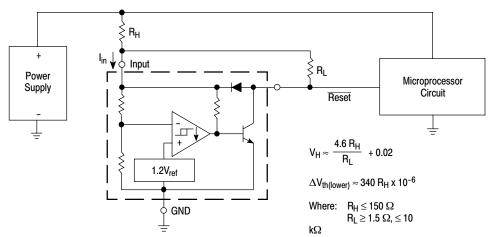


Figure 9. Low Voltage Microprocessor Reset

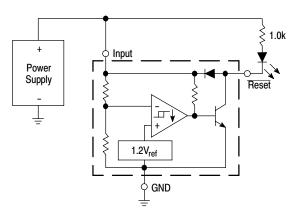


Comparator hysteresis can be increased with the addition of resistor $R_H.$ The hysteresis equation has been simplified and does not account for the change of input current I_{in} as V_{CC} crosses the comparator threshold (Figure 4). An increase of the lower threshold $\Delta V_{th(lower)}$ will be observed due to I_{in} which is typically 340 μA at 4.59 $\,$ V. The equations are accurate to $\pm 10\%$ with R_H less than 150 Ω and R_L between 1.5 $k\Omega$ and 10 $k\Omega$.

TEST DATA

V _H (mV)	ΔV _{th} (mV)	R _H (Ω)	R _L (kΩ)
20	0	0	0
51	3.4	10	1.5
40	6.8	20	4.7
81	6.8	20	1.5
71	10	30	2.7
112	10	30	1.5
100	16	47	2.7
164	16	47	1.5
190	34	100	2.7
327	34	100	1.5
276	51	150	2.7
480	51	150	1.5

Figure 10. Low Voltage Microprocessor Reset with Additional Hysteresis



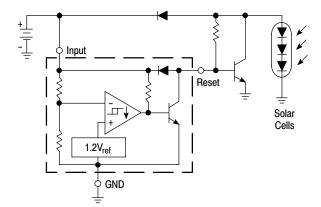


Figure 11. Voltage Monitor

Figure 12. Solar Powered Battery Charger

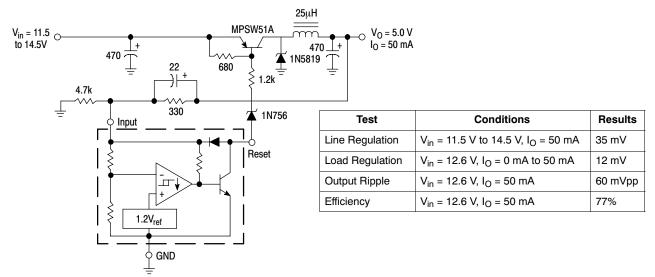
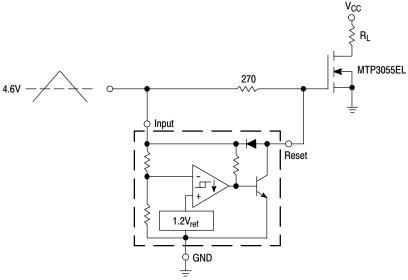


Figure 13. Low Power Switching Regulator



Overheating of the logic level power MOSFET due to insufficient gate voltage can be prevented with the above circuit. When the input signal is below the 4.6 V threshold of the MC34064, its output grounds the gate of the L^2 MOSFET.

Figure 14. MOSFET Low Voltage Gate Drive Protection

ORDERING INFORMATION

Device	Operating Temperature Range	Package	Shipping [†]
MC34064D-005		SOIC-8	98 Units / Rail
MC34064D-5G		SOIC-8 (Pb-Free)	
MC34064D-5R2		SOIC-8	2500 Units/ Tape & Reel
MC34064D-5R2G		SOIC-8 (Pb-Free)	
MC34064DM-5R2		Micro8	4000 Units / Tape & Reel
MC34064DM-5R2G		Micro8 (Pb-Free)	
MC34064P-005		TO-92	2000 Units / Bag
MC34064P-5G		TO-92 (Pb-Free)	
MC34064P-5RA	$T_A = 0^{\circ}C \text{ to } +70^{\circ}C$	TO-92	2000 Units / Tape & Reel
MC34064P-5RAG		TO-92 (Pb-Free)	
MC34064P-5RP		TO-92	2000 Units / Ammo Pack
MC34064P-5RPG		TO-92 (Pb-Free)	
MC34064P-5RM		TO-92	
MC34064P-5RMG		TO-92 (Pb-Free)	
MC34064SN-5T1		TSOP-5	3000 Units / Tape & Reel
MC34064SN-5T1G		TSOP-5 (Pb-Free)	
MC33064D-005		SOIC-8	98 Units / Rail
MC33064D-5G		SOIC-8 (Pb-Free)	
MC33064D-5R2		SOIC-8	2500 Units / Tape & Reel
MC33064D-5R2G		SOIC-8 (Pb-Free)	
MC33064DM-5R2		Micro8	4000 Units / Tape & Reel
MC33064DM-5R2G		Micro8 (Pb-Free)	
MC33064P-005		TO-92	2000 Units / Bag
MC33064P-5G	T _J = -40°C to +85°C	TO-92 (Pb-Free)	
MC33064P-5RA		TO-92	2000 Units / Tape & Reel
MC33064P-5RAG		TO-92 (Pb-Free)	
MC33064P-5RP	- -	TO-92	2000 Units / Ammo Pack
MC33064P-5RPG		TO-92 (Pb-Free)	
MC33064SN-5T1	<u> </u>	TSOP-5	3000 Units / Tape & Reel
MC33064SN-5T1G	- 1	TSOP-5	

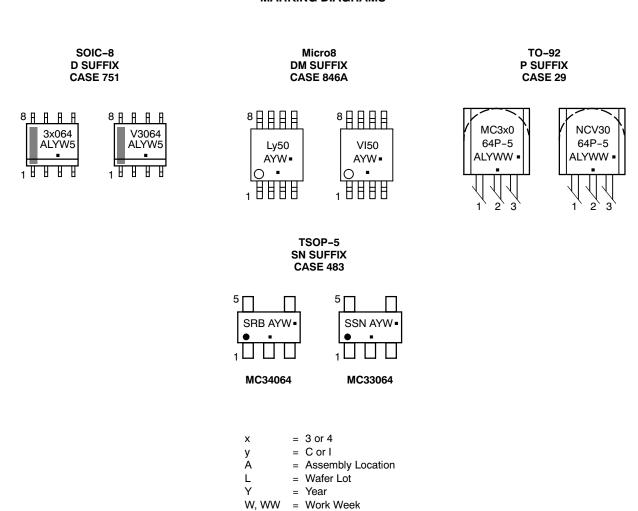
[†]For information on tape and reel specifications, including part orientation and tape sizes, pleaserefer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NCV33064: T_{low} = -40°C, T_{high} = +125°C. Guaranteed by design. NCV prefix is for automotive and other applications requiring site and change control.

ORDERING INFORMATION

Device	Operating Temperature Range	Package	Shipping [†]
NCV33064D-5R2*		SOIC-8	2500 Units / Tape & Reel
NCV33064D-5R2G*		SOIC-8 (Pb-Free)	
NCV33064P-5RA*	1	TO-92	2000 Units / Tape & Reel
NCV33064P-5RAG*	T 4000 to 40500	TO-92 (Pb-Free)	
NCV33064P-5RP*	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	TO-92	2000 Units / Ammo Pack
NCV33064P-5RPG*		TO-92 (Pb-Free)	
NCV33064DM-5R2*	1	Micro8	4000 Units / Tape & Reel
NCV33064DM-5R2G*		Micro8 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, pleaserefer to our Tape and Reel Packaging

MARKING DIAGRAMS



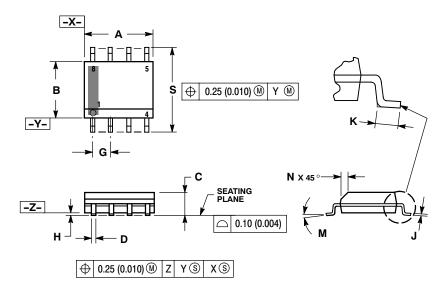
(Note: Microdot may be in either location)

= Pb-Free Package

Specifications Brochure, BRD8011/D. *NCV33064: T_{low} = -40°C, T_{high} = +125°C. Guaranteed by design. NCV prefix is for automotive and other applications requiring site and change control.

PACKAGE DIMENSIONS

SOIC-8 **D SUFFIX** CASE 751-07 **ISSUE AH**

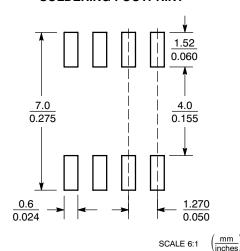


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- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 751-01 THBIL 75-106 APE ORSOLETE NEW
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.050 BSC	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

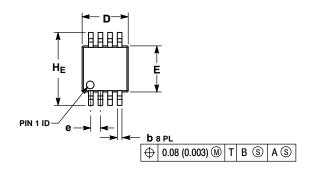
SOLDERING FOOTPRINT*

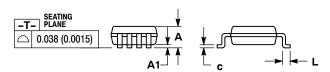


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

Micro8 **DM SUFFIX** CASE 846A-02 ISSUE G





- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

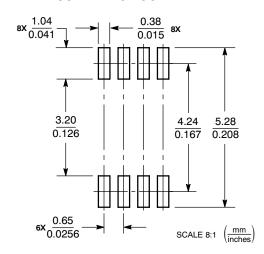
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED AND REPORTS. 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α			1.10			0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
С	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
е	0.65 BSC			0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
HE	4.75	4.90	5.05	0.187	0.193	0.199

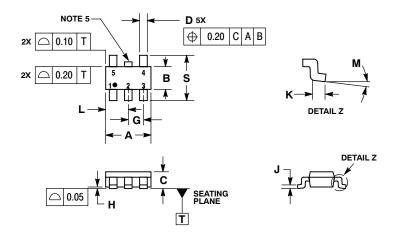
SOLDERING FOOTPRINT*



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PACKAGE DIMENSIONS

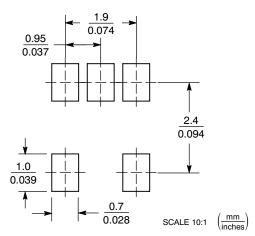
TSOP-5 **SN SUFFIX** CASE 483-02 **ISSUE H**



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 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
 5. OPTIONAL CONSTRUCTION: AN
- BUHRS.
 OPTIONAL CONSTRUCTION: AN
 ADDITIONAL TRIMMED LEAD IS ALLOWED
 IN THIS LOCATION. TRIMMED LEAD NOT TO
 EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS		
DIM	MIN	MAX	
Α	3.00	BSC	
В	1.50	BSC	
C	0.90	1.10	
D	0.25 0.50		
G	0.95	BSC	
H	0.01 0.10		
7	0.10	0.26	
K	0.20 0.60		
L	1.25 1.55		
М	0° 10°		
S	2.50 3.00		

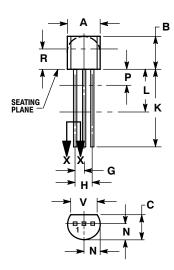
SOLDERING FOOTPRINT*



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PACKAGE DIMENSIONS

TO-92 (TO-226) **P SUFFIX** CASE 29-11 ISSUE AM

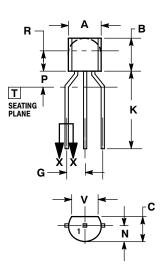


STRAIGHT LEAD **BULK PACK**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- 114.3W, 1902.
 CONTROLLING DIMENSION: INCH.
 CONTOUR OF PACKAGE BEYOND DIMENSION R
 IS UNCONTROLLED.
 LEAD DIMENSION IS UNCONTROLLED IN P AND
- BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	-	12.70	
L	0.250	-	6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	



BENT LEAD TAPE & REEL AMMO PACK



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

		MILLIMETERS			
l	DIM	MIN	MAX		
	Α	4.45	5.20		
	В	4.32	5.33		
[С	3.18	4.19		
[D	0.40	0.54		
[G	2.40	2.80		
	J	0.39	0.50		
	K	12.70			
[N	2.04	2.66		
[P	1.50	4.00		
[R	2.93			
I	٧	3.43			

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